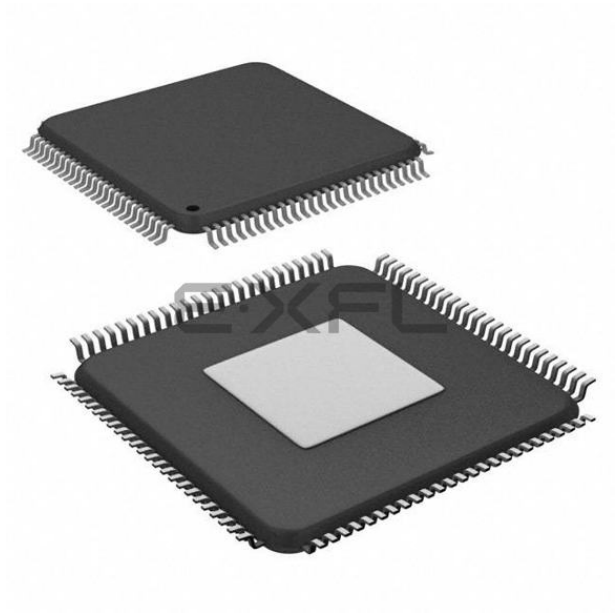
Infineon Technologies - XC2365A104F80LRABKXUMA1 Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	C166SV2
Core Size	16/32-Bit
Speed	80MHz
Connectivity	CANbus, EBI/EMI, I²C, LINbus, SPI, SSC, UART/USART, USI
Peripherals	I²S, POR, PWM, WDT
Number of I/O	75
Program Memory Size	832KB (832K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	50K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP Exposed Pad
Supplier Device Package	PG-LQFP-100-8
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc2365a104f80lrabkxuma1

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16/32-Bit Single-Chip Microcontroller with 32-Bit Performance

XC236xA (XC2000 Family)

1 Summary of Features

For a quick overview and easy reference, the features of the XC236xA are summarized here.

- High-performance CPU with five-stage pipeline and MPU
  - 12.5 ns instruction cycle at 80 MHz CPU clock (single-cycle execution)
  - One-cycle 32-bit addition and subtraction with 40-bit result
  - One-cycle multiplication (16 × 16 bit)
  - Background division (32 / 16 bit) in 21 cycles
  - One-cycle multiply-and-accumulate (MAC) instructions
  - Enhanced Boolean bit manipulation facilities
  - Zero-cycle jump execution
  - Additional instructions to support HLL and operating systems
  - Register-based design with multiple variable register banks
  - Fast context switching support with two additional local register banks
  - 16 Mbytes total linear address space for code and data
  - 1024 Bytes on-chip special function register area (C166 Family compatible)
  - Integrated Memory Protection Unit (MPU)
- Interrupt system with 16 priority levels for up to 96 sources
  - Selectable external inputs for interrupt generation and wake-up
  - Fastest sample-rate 12.5 ns
- Eight-channel interrupt-driven single-cycle data transfer with Peripheral Event Controller (PEC), 24-bit pointers cover total address space
- Clock generation from internal or external clock sources, using on-chip PLL or prescaler
- Hardware CRC-Checker with Programmable Polynomial to Supervise On-Chip Memory Areas
- On-chip memory modules
  - 8 Kbytes on-chip stand-by RAM (SBRAM)
  - 2 Kbytes on-chip dual-port RAM (DPRAM)
  - Up to 16 Kbytes on-chip data SRAM (DSRAM)
  - Up to 32 Kbytes on-chip program/data SRAM (PSRAM)
  - Up to 832 Kbytes on-chip program memory (Flash memory)
  - Memory content protection through Error Correction Code (ECC)
- On-Chip Peripheral Modules
  - Multi-functional general purpose timer unit with 5 timers
  - 16-channel general purpose capture/compare unit (CAPCOM2)
  - Two capture/compare units for flexible PWM signal generation (CCU6x)

Table 6 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
6	P7.0	O0 / I	St/B	**Bit 0 of Port 7, General Purpose Input/Output**
	T3OUT	O1	St/B	**GPT12E Timer T3 Toggle Latch Output**
	T6OUT	O2	St/B	**GPT12E Timer T6 Toggle Latch Output**
	TDO_A	OH / IH	St/B	**JTAG Test Data Output / DAP1 Input/Output** If DAP pos. 0 or 2 is selected during start-up, an internal pull-down device will hold this pin low when nothing is driving it.
	ESR2_1	I	St/B	**ESR2 Trigger Input 1**
7	P7.3	O0 / I	St/B	**Bit 3 of Port 7, General Purpose Input/Output**
	EMUX1	O1	St/B	**External Analog MUX Control Output 1 (ADC1)**
	U0C1_DOUT	O2	St/B	**USIC0 Channel 1 Shift Data Output**
	U0C0_DOUT	O3	St/B	**USIC0 Channel 0 Shift Data Output**
	TMS_C	IH	St/B	**JTAG Test Mode Selection Input** If JTAG pos. C is selected during start-up, an internal pull-up device will hold this pin low when nothing is driving it.
	U0C1_DX0F	I	St/B	**USIC0 Channel 1 Shift Data Input**
8	P7.1	O0 / I	St/B	**Bit 1 of Port 7, General Purpose Input/Output**
	EXTCLK	O1	St/B	**Programmable Clock Signal Output**
	$\overline{\text{BRKIN\_C}}$	I	St/B	**OCDS Break Signal Input**
9	P7.4	O0 / I	St/B	**Bit 4 of Port 7, General Purpose Input/Output**
	EMUX2	O1	St/B	**External Analog MUX Control Output 2 (ADC1)**
	U0C1_DOUT	O2	St/B	**USIC0 Channel 1 Shift Data Output**
	U0C1_SCLKOUT	O3	St/B	**USIC0 Channel 1 Shift Clock Output**
	TCK_C	IH	St/B	**DAP0/JTAG Clock Input** If JTAG pos. C is selected during start-up, an internal pull-up device will hold this pin high when nothing is driving it. If DAP pos. 2 is selected during start-up, an internal pull-down device will hold this pin low when nothing is driving it.
	U0C0_DX0D	I	St/B	**USIC0 Channel 0 Shift Data Input**
	U0C1_DX1E	I	St/B	**USIC0 Channel 1 Shift Clock Input**

Table 6 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
11	P6.0	O0 / I	DA/A	**Bit 0 of Port 6, General Purpose Input/Output**
	EMUX0	O1	DA/A	**External Analog MUX Control Output 0 (ADC0)**
	TxDC2	O2	DA/A	**CAN Node 2 Transmit Data Output**
	$\overline{\text{BRKOUT}}$	O3	DA/A	**OCDS Break Signal Output**
	ADCx_REQGTyG	I	DA/A	**External Request Gate Input for ADC0/1**
	U1C1_DX0E	I	DA/A	**USIC1 Channel 1 Shift Data Input**
12	P6.1	O0 / I	DA/A	**Bit 1 of Port 6, General Purpose Input/Output**
	EMUX1	O1	DA/A	**External Analog MUX Control Output 1 (ADC0)**
	T3OUT	O2	DA/A	**GPT12E Timer T3 Toggle Latch Output**
	U1C1_DOUT	O3	DA/A	**USIC1 Channel 1 Shift Data Output**
	ADCx_REQTRyE	I	DA/A	**External Request Trigger Input for ADC0/1**
	RxDC2E	I	DA/A	**CAN Node 2 Receive Data Input**
	ESR1_6	I	DA/A	**ESR1 Trigger Input 6**
13	P6.2	O0 / I	DA/A	**Bit 2 of Port 6, General Purpose Input/Output**
	EMUX2	O1	DA/A	**External Analog MUX Control Output 2 (ADC0)**
	T6OUT	O2	DA/A	**GPT12E Timer T6 Toggle Latch Output**
	U1C1_SCLKOUT	O3	DA/A	**USIC1 Channel 1 Shift Clock Output**
	U1C1_DX1C	I	DA/A	**USIC1 Channel 1 Shift Clock Input**
15	P15.0	I	In/A	**Bit 0 of Port 15, General Purpose Input**
	ADC1_CH0	I	In/A	**Analog Input Channel 0 for ADC1**
16	P15.2	I	In/A	**Bit 2 of Port 15, General Purpose Input**
	ADC1_CH2	I	In/A	**Analog Input Channel 2 for ADC1**
	T5INA	I	In/A	**GPT12E Timer T5 Count/Gate Input**
17	P15.4	I	In/A	**Bit 4 of Port 15, General Purpose Input**
	ADC1_CH4	I	In/A	**Analog Input Channel 4 for ADC1**
	T6INA	I	In/A	**GPT12E Timer T6 Count/Gate Input**

Table 6 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
59	P10.0	O0 / I	St/B	**Bit 0 of Port 10, General Purpose Input/Output**
	U0C1_DOUT	O1	St/B	**USIC0 Channel 1 Shift Data Output**
	CCU60_CC60	O2	St/B	**CCU60 Channel 0 Output**
	AD0	OH / IH	St/B	**External Bus Interface Address/Data Line 0**
	CCU60_CC60INA	I	St/B	**CCU60 Channel 0 Input**
	ESR1_2	I	St/B	**ESR1 Trigger Input 2**
	U0C0_DX0A	I	St/B	**USIC0 Channel 0 Shift Data Input**
	U0C1_DX0A	I	St/B	**USIC0 Channel 1 Shift Data Input**
60	P10.1	O0 / I	St/B	**Bit 1 of Port 10, General Purpose Input/Output**
	U0C0_DOUT	O1	St/B	**USIC0 Channel 0 Shift Data Output**
	CCU60_CC61	O2	St/B	**CCU60 Channel 1 Output**
	AD1	OH / IH	St/B	**External Bus Interface Address/Data Line 1**
	CCU60_CC61INA	I	St/B	**CCU60 Channel 1 Input**
	U0C0_DX1A	I	St/B	**USIC0 Channel 0 Shift Clock Input**
	U0C0_DX0B	I	St/B	**USIC0 Channel 0 Shift Data Input**
61	P0.3	O0 / I	St/B	**Bit 3 of Port 0, General Purpose Input/Output**
	U1C0_SELO0	O1	St/B	**USIC1 Channel 0 Select/Control 0 Output**
	U1C1_SELO1	O2	St/B	**USIC1 Channel 1 Select/Control 1 Output**
	CCU61_COUT60	O3	St/B	**CCU61 Channel 0 Output**
	A3	OH	St/B	**External Bus Interface Address Line 3**
	U1C0_DX2A	I	St/B	**USIC1 Channel 0 Shift Control Input**
	RxDC0B	I	St/B	**CAN Node 0 Receive Data Input**

Table 6 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
62	P10.2	O0 / I	St/B	**Bit 2 of Port 10, General Purpose Input/Output**
	U0C0_SCLKOUT	O1	St/B	**USIC0 Channel 0 Shift Clock Output**
	CCU60_CC62	O2	St/B	**CCU60 Channel 2 Output**
	AD2	OH / IH	St/B	**External Bus Interface Address/Data Line 2**
	CCU60_CC62INA	I	St/B	**CCU60 Channel 2 Input**
	U0C0_DX1B	I	St/B	**USIC0 Channel 0 Shift Clock Input**
63	P0.4	O0 / I	St/B	**Bit 4 of Port 0, General Purpose Input/Output**
	U1C1_SELO0	O1	St/B	**USIC1 Channel 1 Select/Control 0 Output**
	U1C0_SELO1	O2	St/B	**USIC1 Channel 0 Select/Control 1 Output**
	CCU61_COUT61	O3	St/B	**CCU61 Channel 1 Output**
	A4	OH	St/B	**External Bus Interface Address Line 4**
	U1C1_DX2A	I	St/B	**USIC1 Channel 1 Shift Control Input**
	RxDC1B	I	St/B	**CAN Node 1 Receive Data Input**
	ESR2_8	I	St/B	**ESR2 Trigger Input 8**
65	P2.13	O0 / I	St/B	**Bit 13 of Port 2, General Purpose Input/Output**
	U2C1_SELO2	O1	St/B	**USIC2 Channel 1 Select/Control 2 Output**
	RxDC2D	I	St/B	**CAN Node 2 Receive Data Input**
66	P2.10	O0 / I	St/B	**Bit 10 of Port 2, General Purpose Input/Output**
	U0C1_DOUT	O1	St/B	**USIC0 Channel 1 Shift Data Output**
	U0C0_SELO3	O2	St/B	**USIC0 Channel 0 Select/Control 3 Output**
	CC2_CC23	O3 / I	St/B	**CAPCOM2 CC23IO Capture Inp./ Compare Out.**
	A23	OH	St/B	**External Bus Interface Address Line 23**
	U0C1_DX0E	I	St/B	**USIC0 Channel 1 Shift Data Input**
	CAPINA	I	St/B	**GPT12E Register CAPREL Capture Input**

3.4 Memory Protection Unit (MPU)

The XC236xA's Memory Protection Unit (MPU) protects user-specified memory areas from unauthorized read, write, or instruction fetch accesses. The MPU can protect the whole address space including the peripheral area. This completes established mechanisms such as the register security mechanism or stack overrun/underrun detection.

Four Protection Levels support flexible system programming where operating system, low level drivers, and applications run on separate levels. Each protection level permits different access restrictions for instructions and/or data.

Every access is checked (if the MPU is enabled) and an access violating the permission rules will be marked as invalid and leads to a protection trap.

A set of protection registers for each protection level specifies the address ranges and the access permissions. Applications requiring more than 4 protection levels can dynamically re-program the protection registers.

3.5 Memory Checker Module (MCHK)

The XC236xA's Memory Checker Module calculates a checksum (fractional polynomial division) on a block of data, often called Cyclic Redundancy Code (CRC). It is based on a 32-bit linear feedback shift register and may, therefore, also be used to generate pseudo-random numbers.

The Memory Checker Module is a 16-bit parallel input signature compression circuitry which enables error detection within a block of data stored in memory, registers, or communicated e.g. via serial communication lines. It reduces the probability of error masking due to repeated error patterns by calculating the signature of blocks of data.

The polynomial used for operation is configurable, so most of the commonly used polynomials may be used. Also, the block size for generating a CRC result is configurable via a local counter. An interrupt may be generated if testing the current data block reveals an error.

An autonomous CRC compare circuitry is included to enable redundant error detection, e.g. to enable higher safety integrity levels.

The Memory Checker Module provides enhanced fault detection (beyond parity or ECC) for data and instructions in volatile and non volatile memories. This is especially important for the safety and reliability of embedded systems.

to a dedicated vector table location). The occurrence of a hardware trap is also indicated by a single bit in the trap flag register (TFR). Unless another higher-priority trap service is in progress, a hardware trap will interrupt any ongoing program execution. In turn, hardware trap services can normally not be interrupted by standard or PEC interrupts.

Depending on the package option up to 3 External Service Request (ESR) pins are provided. The ESR unit processes their input values and allows to implement user controlled trap functions (System Requests SR0 and SR1). In this way reset, wakeup and power control can be efficiently realized.

Software interrupts are supported by the 'TRAP' instruction in combination with an individual trap (interrupt) number. Alternatively to emulate an interrupt by software a program can trigger interrupt requests by writing the Interrupt Request (IR) bit of an interrupt control register.

3.7 On-Chip Debug Support (OCDS)

The On-Chip Debug Support system built into the XC236xA provides a broad range of debug and emulation features. User software running on the XC236xA can be debugged within the target system environment.

The OCDS is controlled by an external debugging device via the debug interface. This either consists of the 2-pin Device Access Port (DAP) or of the JTAG port conforming to IEEE-1149. The debug interface can be completed with an optional break interface.

The debugger controls the OCDS with a set of dedicated registers accessible via the debug interface (DAP or JTAG). In addition the OCDS system can be controlled by the CPU, e.g. by a monitor program. An injection interface allows the execution of OCDS-generated instructions by the CPU.

Multiple breakpoints can be triggered by on-chip hardware, by software, or by an external trigger input. Single stepping is supported, as is the injection of arbitrary instructions and read/write access to the complete internal address space. A breakpoint trigger can be answered with a CPU halt, a monitor call, a data transfer, or/and the activation of an external signal.

Tracing data can be obtained via the debug interface, or via the external bus interface for increased performance.

Tracing of program execution is supported by the XC2000 Family emulation device.

The DAP interface uses two interface signals, the JTAG interface uses four interface signals, to communicate with external circuitry. The debug interface can be amended with two optional break lines.

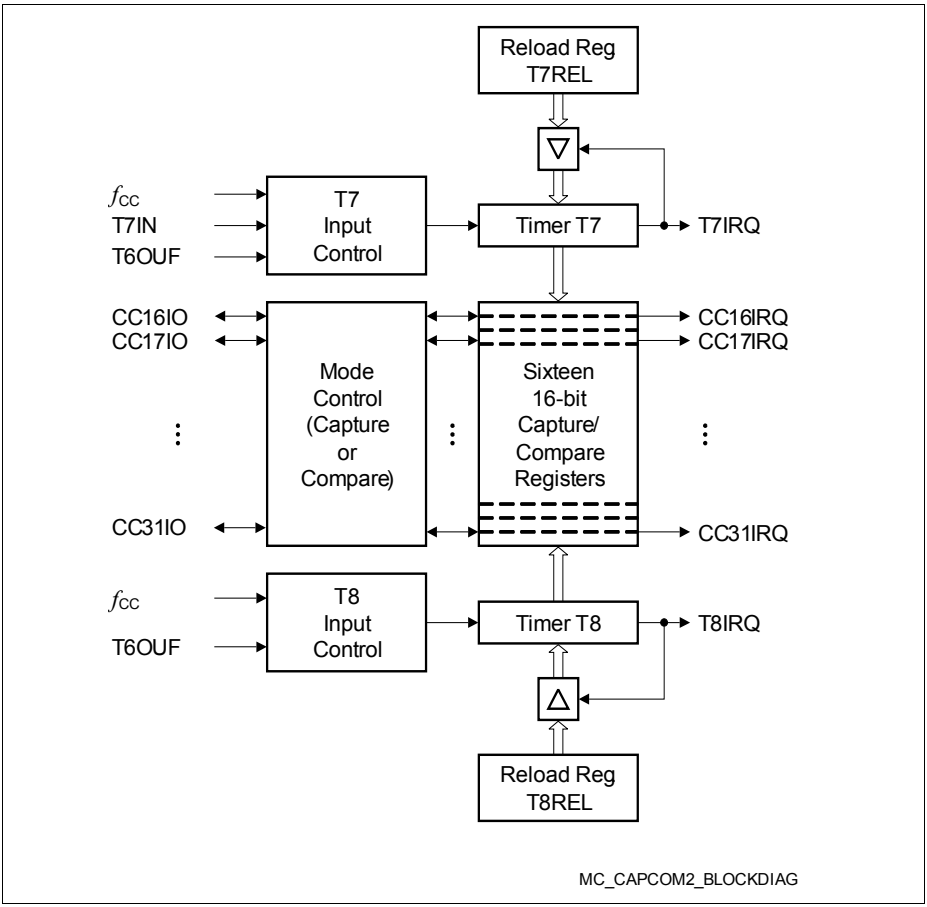

Figure 6 CAPCOM2 Unit Block Diagram

Target Protocols

Each USIC channel can receive and transmit data frames with a selectable data word width from 1 to 16 bits in each of the following protocols:

- **UART** (asynchronous serial channel)
  - module capability: maximum baud rate = f_{SYS} / 4
  - data frame length programmable from 1 to 63 bits
  - MSB or LSB first
- **LIN** Support (Local Interconnect Network)
  - module capability: maximum baud rate = f_{SYS} / 16
  - checksum generation under software control
  - baud rate detection possible by built-in capture event of baud rate generator
- **SSC/SPI** (synchronous serial channel with or without data buffer)
  - module capability: maximum baud rate = f_{SYS} / 2, limited by loop delay
  - number of data bits programmable from 1 to 63, more with explicit stop condition
  - MSB or LSB first
  - optional control of slave select signals
- **IIC** (Inter-IC Bus)
  - supports baud rates of 100 kbit/s and 400 kbit/s
- **IIS** (Inter-IC Sound Bus)
  - module capability: maximum baud rate = f_{SYS} / 2

Note: Depending on the selected functions (such as digital filters, input synchronization stages, sample point adjustment, etc.), the maximum achievable baud rate can be limited. Please note that there may be additional delays, such as internal or external propagation delays and driver delays (e.g. for collision detection in UART mode, for IIC, etc.).

3.16 Watchdog Timer

The Watchdog Timer is one of the fail-safe mechanisms which have been implemented to prevent the controller from malfunctioning for longer periods of time.

The Watchdog Timer is always enabled after an application reset of the chip. It can be disabled and enabled at any time by executing the instructions DISWDT and ENWDT respectively. The software has to service the Watchdog Timer before it overflows. If this is not the case because of a hardware or software failure, the Watchdog Timer overflows, generating a prewarning interrupt and then a reset request.

The Watchdog Timer is a 16-bit timer clocked with the system clock divided by 16,384 or 256. The Watchdog Timer register is set to a prespecified reload value (stored in WDTREL) in order to allow further variation of the monitored time interval. Each time it is serviced by the application software, the Watchdog Timer is reloaded and the prescaler is cleared.

Time intervals between 3.2 µs and 13.42 s can be monitored (@ 80 MHz).
The default Watchdog Timer interval after power-up is 6.5 ms (@ 10 MHz).

3.17 Clock Generation

The Clock Generation Unit can generate the system clock signal f_{SYS} for the XC236xA from a number of external or internal clock sources:

- External clock signals with pad voltage or core voltage levels
- External crystal or resonator using the on-chip oscillator
- On-chip clock source for operation without crystal/resonator
- Wake-up clock (ultra-low-power) to further reduce power consumption

The programmable on-chip PLL with multiple prescalers generates a clock signal for maximum system performance from standard crystals, a clock input signal, or from the on-chip clock source. See also **Section 4.6.2**.

The Oscillator Watchdog (OWD) generates an interrupt if the crystal oscillator frequency falls below a certain limit or stops completely. In this case, the system can be supplied with an emergency clock to enable operation even after an external clock failure.

All available clock signals can be output on one of two selectable pins.

3.18 Parallel Ports

The XC236xA provides up to 76 I/O lines which are organized into 7 input/output ports and 2 input ports. All port lines are bit-addressable, and all input/output lines can be individually (bit-wise) configured via port control registers. This configuration selects the direction (input/output), push/pull or open-drain operation, activation of pull devices, and edge characteristics (shape) and driver characteristics (output current) of the port drivers. The I/O ports are true bidirectional ports which are switched to high impedance state when configured as inputs. During the internal reset, all port pins are configured as inputs without pull devices active.

All port lines have alternate input or output functions associated with them. These alternate functions can be programmed to be assigned to various port pins to support the best utilization for a given application. For this reason, certain functions appear several times in **Table 10**.

All port lines that are not used for alternate functions may be used as general purpose I/O lines.

Table 10 Summary of the XC236xA's Ports

Port	Width	I/O	Connected Modules
P0	8	I/O	EBC (A7…A0), CCU6, USIC, CAN
P1	8	I/O	EBC (A15…A8), CCU6, USIC
P2	14	I/O	EBC (READY, $\overline{\text{BHE}}$, A23…A16, AD15…AD13, D15…D13), CAN, CC2, GPT12E, USIC, DAP/JTAG
P4	4	I/O	EBC ($\overline{\text{CS3}}$…$\overline{\text{CS0}}$), CC2, CAN, GPT12E, USIC
P5	11	I	Analog Inputs, CCU6, DAP/JTAG, GPT12E, CAN
P6	3	I/O	ADC, CAN, GPT12E
P7	5	I/O	CAN, GPT12E, SCU, DAP/JTAG, CCU6, ADC, USIC
P10	16	I/O	EBC (ALE, $\overline{\text{RD}}$, $\overline{\text{WR}}$, AD12…AD0, D12…D0), CCU6, USIC, DAP/JTAG, CAN
P15	5	I	Analog Inputs, GPT12E

4.1.2 Operating Conditions

The following operating conditions must not be exceeded to ensure correct operation of the XC236xA. All parameters specified in the following sections refer to these operating conditions, unless otherwise noticed.

Note: Typical parameter values refer to room temperature and nominal supply voltage, minimum/maximum parameter values also include conditions of minimum/maximum temperature and minimum/maximum supply voltage. Additional details are described where applicable.

Table 13 Operating Conditions

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Voltage Regulator Buffer Capacitance for DMP_M	C_{EVRM} SR	1.0	–	4.7	µF	1)
Voltage Regulator Buffer Capacitance for DMP_1	C_{EVR1} SR	0.47	–	2.2	µF	1)2)
External Load Capacitance	C_L SR	–	20[3)]	–	pF	pin out driver= default 4)
System frequency	f_{SYS} SR	–	–	100	MHz	5)
Overload current for analog inputs[6)]	I_{OVA} SR	-2	–	5	mA	not subject to production test
Overload current for digital inputs[6)]	I_{OVD} SR	-5	–	5	mA	not subject to production test
Overload current coupling factor for analog inputs[7)]	K_{OVA} CC	–	2.5×10^{-4}	1.5×10^{-3}	-	$I_{OV} < 0$ mA; not subject to production test
		–	1.0×10^{-6}	1.0×10^{-4}	-	$I_{OV} > 0$ mA; not subject to production test
Overload current coupling factor for digital I/O pins	K_{OVD} CC	–	1.0×10^{-2}	3.0×10^{-2}		$I_{OV} < 0$ mA; not subject to production test
		–	1.0×10^{-4}	5.0×10^{-3}		$I_{OV} > 0$ mA; not subject to production test

4.2.3 Power Consumption

The power consumed by the XC236xA depends on several factors such as supply voltage, operating frequency, active circuits, and operating temperature. The power consumption specified here consists of two components:

- The switching current I_S depends on the device activity
- The leakage current I_{LK} depends on the device temperature

To determine the actual power consumption, always both components, switching current I_S and leakage current I_{LK} must be added:

$I_{DDP} = I_S + I_{LK}$.

Note: The power consumption values are not subject to production test. They are verified by design/characterization.
To determine the total power consumption for dimensioning the external power supply, also the pad driver currents must be considered.

The given power consumption parameters and their values refer to specific operating conditions:

- **Active mode**:
  Regular operation, i.e. peripherals are active, code execution out of Flash.
- **Stopover mode**:
  Crystal oscillator and PLL stopped, Flash switched off, clock in domain DMP_1 stopped.

Note: The maximum values cover the complete specified operating range of all manufactured devices.
The typical values refer to average devices under typical conditions, such as nominal supply voltage, room temperature, application-oriented activity.
After a power reset, the decoupling capacitors for V_{DDIM} and V_{DDI1} are charged with the maximum possible current.

For additional information, please refer to **Section 5.2, Thermal Considerations**.

Note: Operating Conditions apply.

Table 16 Switching Power Consumption

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Power supply current (active) with all peripherals active and EVVRs on	I_{SACT} CC	–	10 + 0.6 x f_{SYS} [1]	10 + 1.0 x f_{SYS} [1]	mA	2)3)
Power supply current in stopover mode, EVVRs on	I_{SSO} CC	–	0.7	2.0	mA	

1) f_{SYS} in MHz.

Table 17 Leakage Power Consumption

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Leakage supply current (DMP_1 powered)[1]	I_{LK1} CC	–	0.03	0.05	mA	T_J= 25 °C[1]
		–	0.5	1.3	mA	T_J= 85 °C[1]
		–	2.1	6.2	mA	T_J= 125 °C[1]
		–	4.4	13.7	mA	T_J= 150 °C[1]

1) All inputs (including pins configured as inputs) are set at 0 V to 0.1 V or at V_{DDP} - 0.1 V to V_{DDP} and all outputs (including pins configured as outputs) are disconnected.

Note: A fraction of the leakage current flows through domain DMP_A (pin V_{DDPA}). This current can be calculated as 7 000 $\times$ e$^{-\alpha}$, with α = 5 000 / (273 + 1.3$\times T_J$). For T_J = 150°C, this results in a current of 160 μA.

The leakage power consumption can be calculated according to the following formulas:

I_{LK0} = 500 000 × e$^{-\alpha}$, with α = 3 000 / (273 + B$\times T_J$)

Parameter B must be replaced by

- 1.0 for typical values
- 1.6 for maximum values

I_{LK1} = 600 000 × e$^{-\alpha}$, with α = 5 000 / (273 + B$\times T_J$)

Parameter B must be replaced by

- 1.0 for typical values
- 1.3 for maximum values

4.6.5 External Bus Timing

The following parameters specify the behavior of the XC236xA bus interface.

Note: These parameters are not subject to production test but verified by design and/or characterization.

Note: Operating Conditions apply.

Bus Interface Performance Limits

The output frequency at the bus interface pins is limited by the performance of the output drivers. The fast clock driver (used for CLKOUT) can drive 80-MHz signals, the standard drivers can drive 40-MHz signals
Therefore, the speed of the EBC must be limited, either by limiting the system frequency to $f_{SYS} \leq 80$ MHz or by adding waitstates so that signal transitions have a minimum distance of 12.5 ns.
For a description of the bus protocol and the programming of its variable timing parameters, please refer to the User's Manual.

Table 28 EBC Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
CLKOUT Cycle Time[1)]	t_5 CC	–	1 / f_{SYS}	–	ns	
CLKOUT high time	t_6 CC	2	–	–		
CLKOUT low time	t_7 CC	2	–	–		
CLKOUT rise time	t_8 CC	–	–	3	ns	
CLKOUT fall time	t_9 CC	–	–	3		

1) The CLKOUT cycle time is influenced by PLL jitter. For longer periods the relative deviation decreases (see PLL deviation formula).

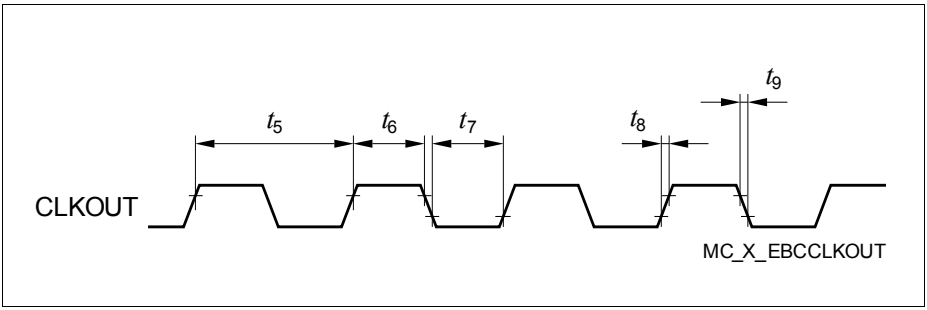

Figure 22 CLKOUT Signal Timing

Table 31 EBC External Bus Timing for Lower Voltage Range

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Output valid delay for $\overline{RD}$, $\overline{WR}$($\overline{L}$/$\overline{H}$)	t_{10} CC	–	11	20	ns	
Output valid delay for $\overline{BHE}$, ALE	t_{11} CC	–	10	21	ns	
Address output valid delay for A23 ... A0	t_{12} CC	–	11	22	ns	
Address output valid delay for AD15 ... AD0 (MUX mode)	t_{13} CC	–	10	22	ns	
Output valid delay for $\overline{CS}$	t_{14} CC	–	10	13	ns	
Data output valid delay for AD15 ... AD0 (write data, MUX mode)	t_{15} CC	–	10	22	ns	
Data output valid delay for D15 ... D0 (write data, DEMUX mode)	t_{16} CC	–	10	22	ns	
Output hold time for $\overline{RD}$, $\overline{WR}$($\overline{L}$/$\overline{H}$)	t_{20} CC	-2	8	10	ns	
Output hold time for $\overline{BHE}$, ALE	t_{21} CC	-2	8	10	ns	
Address output hold time for AD15 ... AD0	t_{23} CC	-3	8	10	ns	
Output hold time for $\overline{CS}$	t_{24} CC	-3	8	11	ns	
Data output hold time for D15 ... D0 and AD15 ... AD0	t_{25} CC	-3	8	10	ns	
Input setup time for READY, D15 ... D0, AD15 ... AD0	t_{30} SR	29	17	–	ns	
Input hold time READY, D15 ... D0, AD15 ... AD0[1)]	t_{31} SR	0	-9	–	ns	

1) Read data are latched with the same internal clock edge that triggers the address change and the rising edge of $\overline{RD}$. Address changes before the end of $\overline{RD}$ have no impact on (demultiplexed) read cycles. Read data can change after the rising edge of $\overline{RD}$.

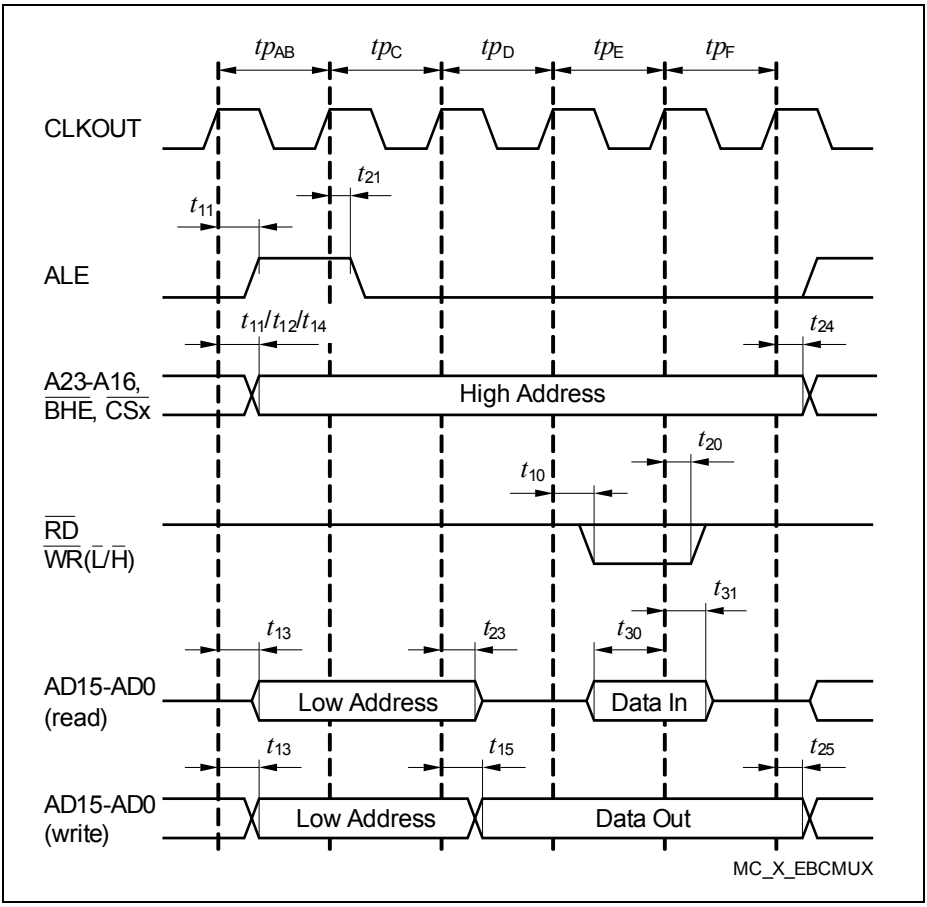

Figure 23 Multiplexed Bus Cycle

Table 33 USIC SSC Master Mode Timing for Lower Voltage Range (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Receive data input setup time to SCLKOUT receive edge	t_4 SR	40	–	–	ns	
Data input DX0 hold time from SCLKOUT receive edge	t_5 SR	-5	–	–	ns	

1) $t_{SYS} = 1 / f_{SYS}$

Table 34 USIC SSC Slave Mode Timing for Upper Voltage Range

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Select input DX2 setup to first clock input DX1 transmit edge[1)]	t_{10} SR	7	–	–	ns	
Select input DX2 hold after last clock input DX1 receive edge[1)]	t_{11} SR	7	–	–	ns	
Receive data input setup time to shift clock receive edge[1)]	t_{12} SR	7	–	–	ns	
Data input DX0 hold time from clock input DX1 receive edge[1)]	t_{13} SR	5	–	–	ns	
Data output DOUT valid time	t_{14} CC	7	–	33	ns	

1) These input timings are valid for asynchronous input signal handling of slave select input, shift clock input, and receive data input (bits DXnCR.DSEN = 0).

Debug via JTAG

The following parameters are applicable for communication through the JTAG debug interface. The JTAG module is fully compliant with IEEE1149.1-2000.

Note: These parameters are not subject to production test but verified by design and/or characterization.

Note: Operating Conditions apply; C_L= 20 pF.

Table 38 JTAG Interface Timing for Upper Voltage Range

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
TCK clock period	t_1 SR	50[1]	–	–	ns	[2]
TCK high time	t_2 SR	16	–	–	ns	
TCK low time	t_3 SR	16	–	–	ns	
TCK clock rise time	t_4 SR	–	–	8	ns	
TCK clock fall time	t_5 SR	–	–	8	ns	
TDI/TMS setup to TCK rising edge	t_6 SR	6	–	–	ns	
TDI/TMS hold after TCK rising edge	t_7 SR	6	–	–	ns	
TDO valid from TCK falling edge (propagation delay)[3]	t_8 CC	–	25	29	ns	
TDO high impedance to valid output from TCK falling edge[4][3]	t_9 CC	–	25	29	ns	
TDO valid output to high impedance from TCK falling edge[3]	t_{10} CC	–	25	29	ns	
TDO hold after TCK falling edge[3]	t_{18} CC	5	–	–	ns	

1) The debug interface cannot operate faster than the overall system, therefore $t_1 \geq t_{SYS}$.
2) Under typical conditions, the interface can operate at transfer rates up to 20 MHz.
3) The falling edge on TCK is used to generate the TDO timing.
4) The setup time for TDO is given implicitly by the TCK cycle time.